

NC7SZ126 TinyLogic[®] UHS Buffer with Three-State Output

Features

- Ultra-High Speed: t_{PD} 2.6ns (Typical) into 50pF at 5V V_{CC}
- High Output Drive: ±24mA at 3V V_{CC}
- Broad V_{CC} Operating Range: 1.65V to 5.5V
- Matches Performance of LCX Operated at 3.3V V_{CC}
- Pow er Dow n High-Impedance Inputs/Outputs
- Over-Voltage Tolerance Inputs Facilitate 5V to 3V Translation
- Proprietary Noise/EMI Reduction Circuitry
- Ultra-Small MicroPak™ Packages
- Space-Saving SOT23 and SC70 Packages

Description

The NC7SZ126 is single buffer with three-State output from ON Semiconductor's Ultra-High Speed (UHS) series of TinyLogic®. The device is fabricated with advanced CMOS technology to achieve ultra-high speed with high output drive while maintaining low static power dissipation over a broad $V_{\rm CC}$ operating range. The device is specified to operate over the 1.65V to 5.5V $V_{\rm CC}$ operating range. The inputs and output are high impedance above ground when $V_{\rm CC}$ is 0V. Inputs tolerate voltages up to 6V, independent of $V_{\rm CC}$ operating voltage. The output tolerates voltages above $V_{\rm CC}$ in the 3-State condition.

Ordering Information

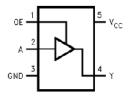
Part Number	Top Mark	Ø Eco Status	Package	Packing Method
NC7SZ126M5X	7Z26	RoHS	5-Lead SOT23, JEDEC MO-178 1.6mm	3000 Units on Tape & Reel
NC7SZ126P5X	Z26	RoHS	5-Lead SC70, EIAJ SC-88a, 1.25mm Wide	3000 Units on Tape & Reel
NC7SZ126L6X	FF	RoHS	6-Lead MicroPak™, 1.00mm Wide	5000 Units on Tape & Reel
NC7SZ126FHX	FF	Green	6-Lead, MicroPak2, 1x1mm Body, .35mm Pitch	5000 Units on Tape & Reel

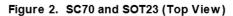
Connection Diagrams



Figure 1. Logic Symbol

Pin Configurations





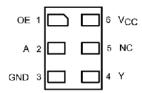


Figure 3. MicroPak (Top Through View)

Pin Definitions

Pin # SC70 / SOT23	Pin # MicroPak	Name	Description
1	1	OE	Input
2	2	А	Input
3	3	GND	Ground
4	4	Y	Output
5	6	V _{CC}	Supply Voltage
	5	NC	No Connect

Function Table

Inputs		Output
OE	Α	Out Y
Н	L	L
Н	Н	н
L	Х	Z

H = HIGH Logic Level

L = LOW Logic Level

X = HIGH or LOW Logic Level

Z = HIGH Impedance State

Absolute Maximum Ratings

Stresses exceeding the absolute maximum ratings may damage the device. The device may not function or be operable above the recommended operating conditions and stressing the parts to these levels is not recommended. In addition, extended exposure to stresses above the recommended operating conditions may affect device reliability. The absolute maximum ratings are stress ratings only.

Symbol	Parameter		Min.	Max.	Unit
V _{CC}	Supply Voltage		-0.5	6.0	V
V _{IN}	DC Input Voltage		-0.5	6.0	V
V _{OUT}	DC Output Voltage		-0.5	6.0	V
	DC Input Diada Current	V _{IN} < -0.5V		-50	m A
lικ	DC Input Diode Current	V _{IN} > 6.0V		+20	- mA
	DC Output Diada Current	V _{OUT} < -0.5V		-50	mΛ
l _{ok}	DC Output Diode Current	V _{OUT} > 6V, V _{CC} =GND		+20	- mA
l _{out}	DC Output Current	DC Output Current			mA
I _{CC} or I _{GND}	DC V _{CC} or Ground Current	DC V _{CC} or Ground Current			mA
T _{STG}	Storage Temperature Range		-65	+150	°C
TJ	Junction Temperature Under Bia	as		+150	°C
T _L	Junction Lead Temperature (So	ldering, 10 Seconds)		+260	°C
		SOT-23		200	
В	Pow or Discipation at ±95°C	SC70-5		150] m\//
P_D	Pow er Dissipation at +85°C	MicroPak-6		130	mW
		MicroPak2-6		120]
ESD	Human Body Model, JEDEC:JES	D22-A114		4000	V
ESD	Charge Device Model, JEDEC:JE	Charge Device Model, JEDEC:JESD22-C101]

Recommended Operating Conditions

The Recommended Operating Conditions table defines the conditions for actual device operation. Recommended operating conditions are specified to ensure optimal performance to the datasheet specifications. ON Semiconductor does not recommend exceeding them or designing to Absolute Maximum Ratings.

Symbol	Parameter	Conditions	Min.	Max.	Unit
W	Supply Voltage Operating		1.65	5.50	V
V _{CC}	Supply Voltage Data Retention		1.50	5.50]
V _{IN}	Input Voltage		0	5.5	V
	V Output Voltage	Active State	0	V _{cc}	V
V _{OUT}	Output Voltage	Three-State	0	5.5]
T _A	Operating Temperature		-40	+85	°C
	Input Rise and Fall Times	V _{CC} =1.8V, 2.5V ± 0.2V	0	20	
t_r, t_f		V _{CC} =3.3V ± 0.3V	0	10	ns/V
		V _{CC} =5.0V ± 0.5V	0	5]

	θ _{JA} Thermal Resistance		SOT-23	300	
		SC70-5	425	°C/W	
			MicroPak-6	500	C/VV
			MicroPak2-6	560	

Note:

1. Unused inputs must be held HIGH or LOW. They may not float.

DC Electrical Characteristics

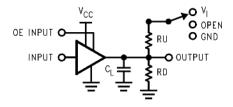
Cum h = !	Daram c to :	v	Conditions	т,	_A =+25°	С	T _A =-40 t	to +85°C	Units	
Sym bol	Parameter	V _{cc}	Conditions	Min.	Тур.	Max.	Min.	Max.	Units	
V _{IH}	HIGH Level	1.65 to 1.95		0.75V _{cc}			0.75V _{cc}		V	
VIH	Input Voltage	2.30 to 5.50		0.70V _{cc}			0.70V _{cc}		V	
V _{IL}	LOW Level	1.65 to 1.95				0.25V _∞		0.25V _∞	c V	
VIL	Input Voltage	2.30 to 5.50				0.30V _∞		0.30V _∞	V	
		1.65		1.55	1.65		1.55			
		1.80		1.70	1.80		1.70			
		2.30	V _{IN} =V _{IH} , I _{OH} =-100μA	2.20	2.30		2.20			
		3.00]	2.90	3.00		2.90			
	HIGH Level	4.50]	4.40	4.50		4.40		V	
V _{OH}	Output Voltage	1.65	I _{OH} =-4mA	1.29	1.52		1.29		V	
		2.30	I _{OH} =-8mA	1.90	2.15		1.90			
		3.00	I _{он} =-16mA	2.40	2.80		2.40			
		3.00	I _{OH} =-24mA	2.30	2.68		2.30			
		4.50	I _{OH} =-32mA	3.80	4.20		3.80			
		1.65			0.00	0.10		0.10		
		1.80]		0.00	0.10		0.10		
		2.30	V _{IN} =V _{IL} ,I _{OL} =100μA		0.00	0.10		0.10		
		3.00	1		0.00	0.10		0.10		
	LOW Level	4.50	1		0.00	0.10		0.10		
V_{OL}	Output Voltage	1.65	I _{OL} =4mA		0.80	0.24		0.24	V	
		2.30	I _{OL} =8mA		0.10	0.30		0.30		
		3.00	I _{OL} =16mA		0.15	0.40		0.40		
		3.00	I _{OL} =24mA		0.22	0.55		0.55		
		4.50	I _{OL} =32mA		0.22	0.55		0.55		
I _{IN}	Input Leakage Current	0 to 5.5	V _{IN} =5.5V, GND			±1		±10	μA	
l _{oz}	3-STATE Output Leakage	0 to 5.5	V _{IN} =V _{IH} or V _{IL} V _O =V _{CC} or GND			±1		±10	μА	
I _{OFF}	Power Off Leakage Current	0	V _{IN} or V _{OUT} =5.5V			1		10	μА	
I _{cc}	Quiescent Supply Current	1.65 to 5.50	V _{IN} =5.5V, GND			2		20	μA	

AC Electrical Characteristics

Symbol	Param eter Param eter	v	Conditions		T _A =25°	С	T _A =-40 1	to +85°C	Units	Figure
Symbol	Parameter	V _{cc}	Conditions	Min.	Тур.	Max.	Min.	Max.	Units	Figure
		1.65		2.0	6.4	13.2	2.0	13.8		
		1.80	C _L =15pF,	2.0	5.3	11.0	2.0	11.5]	
		2.50 ± 0.20	R ₀ =1MΩ	0.8	3.4	7.5	0.8	8.0]	
t _{PLH} , t _{PHL}	Propagation Delay	3.30 ± 0.30	S₁=OPEN	0.5	2.5	5.2	0.5	5.5	ns	Figure 4
TELN, TENE	Tropagation Bolay	5.00 ± 0.50		0.5	2.1	4.5	0.5	4.8]	Figure 6
	3.30 ± 0.30	C _L =50pF,	1.5	3.2	5.7	1.5	6.0]		
		5.00 ± 0.50	R₀=500Ω S₁=OPEN	0.8	2.6	5.0	0.8	5.3		
		1.65	C _L =50pF,	2.0	8.4	15.0	2.0	15.6		
		1.80	R ₀ =500Ω	2.0	6.1	11.5	2.0	12.0		
t _{PZL} , t _{PZH}	Output Enable Time	2.50 ± 0.20	RU=500Ω S ₁ =GND for t _{PZH} S ₁ =V _{IN} for t _{PZL}	1.5	3.8	8.0	1.5	8.5		
	Time	3.30 ± 0.30		1.5	3.2	5.7	1.5	6.0		
		5.00 ± 0.50	V _{IN} =2•V _{CC}	0.8	2.3	5.0	0.8	5.3		Figure 4
		1.65	C _L =50pF,	2.0	6.5	13.2	2.0	14.5	ns	Figure 6
		1.80	R ₀ =500Ω	2.0	5.6	11.0	2.0	12	1	
$t_{PLZ,}t_{PHZ}$	Output Disable Time	2.50 ± 0.20	RU=500Ω S₁=GND for t _{PH7}	1.0	4.0	8.0	1.0	8.5]	
	Time	3.30 ± 0.30	S ₁ =GND for t _{PHZ}	1.0	3.5	5.7	1.0	6.0]	
		5.00 ± 0.50	V _{IN} =2•V _{CC}	0.5	2.5	4.7	0.5	5.0]	
C _{IN}	Input Capacitance	0.00			4				pF	
Соит	Output Capacitance	0.00			8				pF	
	Power Dissipation	3.30			17					Figure 5
C _{PD}	Capacitance ⁽²⁾	5.00			24				pF	Figure 5

Note:

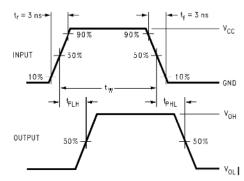
2. C_{PD} is defined as the value of the internal equivalent capacitance which is derived from dynamic operating current consumption (I_{CCD}) at no output lading and operating at 50% duty cycle. C_{PD} is related to I_{CCD} dynamic operating current by the expression: I_{CCD} =(C_{PD})(V_{CC})(I_{IN})+(I_{CC})static).

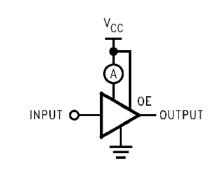


Note:

3. C_L includes load and stray capacitance. Input PRR=1.0MHz, t_W =500ns

Figure 4. AC Test Circuit

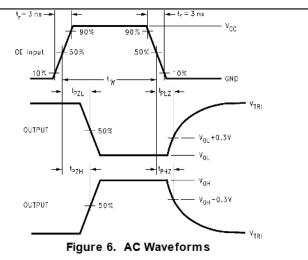




Note:

4. Input=AC Waveform; $t_i=t_f=1.8$ ns; PRR=10MHz; Duty Cycle=50%.

Figure 5. I_{CCD} Test Circuit



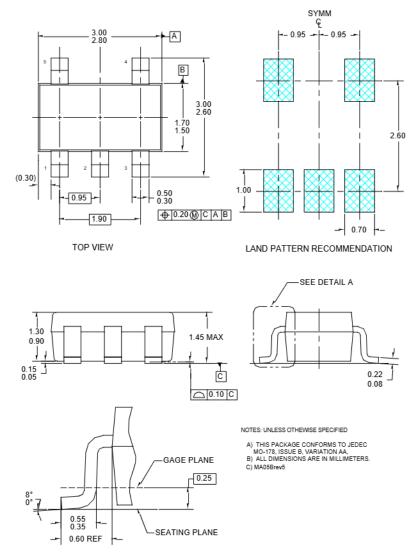


Figure 7. 5-Lead SOT23, JEDEC MO-178 1.6mm

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Package Designator	Tape Section	Cavity Number	Cavity Status	Cover Type Status
	Leader (Start End)	125 (Typical)	Empty	Sealed
M5X	Carrier	3000	Filled	Sealed
	Trailer (Hub End)	75 (Typical)	Empty	Sealed

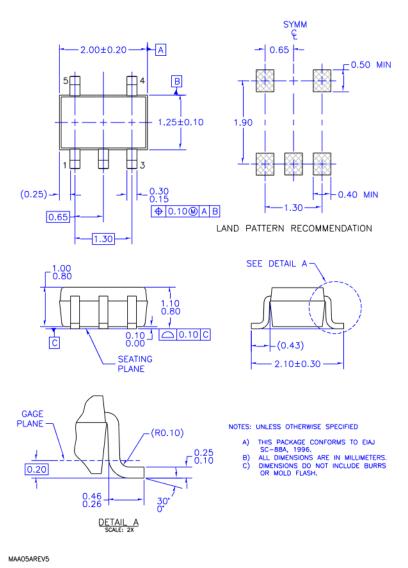
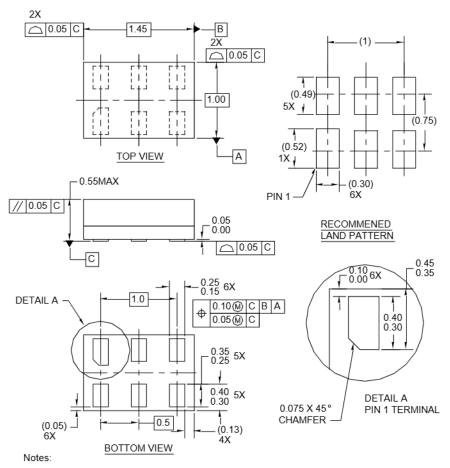


Figure 8. 5-Lead, SC70, EIAJ SC-88a, 1.25mm Wide

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Package Designator	Designator Tape Section		Cavity Status	Cover Type Status
	Leader (Start End)	125 (Typical)	Empty	Sealed
P5X	Carrier	3000	Filled	Sealed
	Trailer (Hub End)	75 (Typical)	Empty	Sealed



- 1. CONFORMS TO JEDEC STANDARD M0-252 VARIATION UAAD
- 2. DIMENSIONS ARE IN MILLIMETERS
- 3. DRAWING CONFORMS TO ASME Y14.5M-1994

MAC06AREVC

Figure 9. 6-Lead, MicroPak™, 1.0mm Wide

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Package Designator	Tape Section	on Cavity Number Cavity Status		Cover Type Status
	Leader (Start End)	125 (Typical)	Empty	Sealed
L6X	Carrier	5000	Filled	Sealed
	Trailer (Hub End)	75 (Typical)	Empty	Sealed

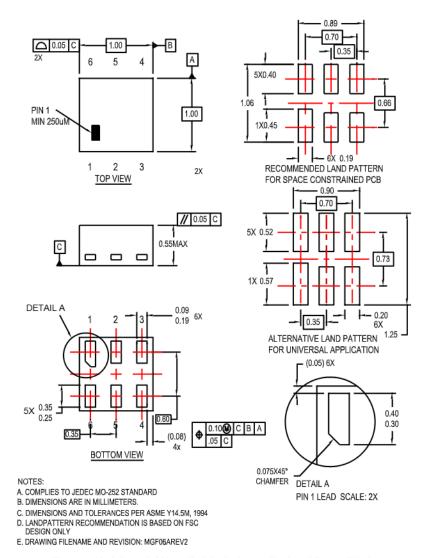


Figure 10.6-Lead, MicroPak2, 1x1mm Body, .35mm Pitch

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Package Designator	Tape Section	ape Section		Cover Type Status
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FHX	Carrier	5000	Filled	Sealed
	Trailer (Hub End)	75 (Typical)	Empty	Sealed

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